

ABSTRACT

An electro-chemical mechanical polishing apparatus has a rotatable platen to support a polishing pad, a carrier head to hold a substrate against the polishing pad, and multiple sensors, e.g., optical sensors or eddy current sensors, spaced at different angular positions about the axis of rotation of the platen. Each of the sensors can be substantially identical. A processor receives the signal from each of the sensors to determines a polishing endpoint.

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